

规格承认书

SPECIFICATION

编号(No):

日期(Date):

客户 (Customer):

品名(Product Name): 片式NTC热敏电阻 Chip NTC thermistor

恭成料号 (QAMCN Part Number): QN0201X103F3435FA

客户规格(Customer's Part Number):

客户承认 CUSTOMER CONFIRM			
承认章 STAMP	核准 APPROVE	审核 CHECK	经办人 SIGNATURE
			

恭成科技有限公司**Quest for Advanced Materials Electronics Co., Ltd.**

营销中心: 广东省深圳市龙华新区观澜银星科技大厦 518109

Marketing Center: Yinxing Technology Building, Guanlan, Longhua new district, Shenzhen 518109

电话 Tel: 0086-755-23732935 传真 Fax: 0086-755-23762516

制造中心: 河北省唐山市曹妃甸工业区中日生态园 063200

Manufactory: Sino-Japan Eco-industrial park, Caofeidian industrial district, Tangshan, Hebei, China 063200

电话 Tel: 0086-315-7332530

网址 Website: <https://www.qamcn.com>邮箱 E-Mail: qam@qamcn.com

变更履历表 Version change history

版本号 Rev.	生效日期 Effective Date	变更内容 Changed Contents	变更原因 Change Reasons	批准 Approved By
01	/	新版发行 New release	/	潘士宾 Shibin Pan

1 外形尺寸 Shape and Dimensions

- 尺寸: 见图 1 和表 1
- PCB 焊盘: 见图 2 和表 1
- Dimensions: See Fig.1 and Table 1.
- Recommended PCB pattern for reflow soldering: See Fig.2 and Table 1

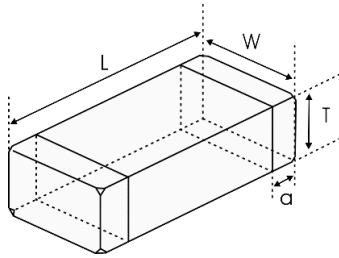


图 1 Fig.1

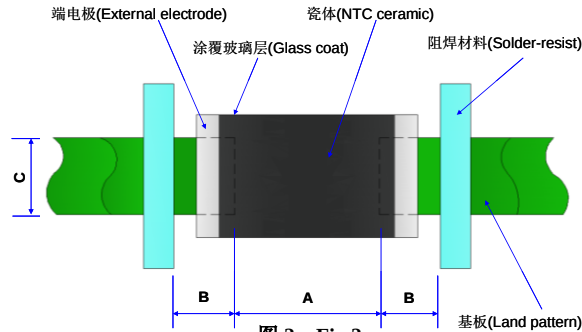


图 2 Fig.2

表 1 (Table 1)

单位 unit: inch[mm]

类别 Type	L	W	T	a	A	B	C
0201 [0603]	0.024±0.002 [0.6±0.05]	0.012±0.002 [0.3±0.05]	0.012±0.002 [0.3±0.05]	0.006±0.002 [0.15±0.05]	[0.2-0.3]	[0.25-0.35]	[0.25-0.35]

2 产品标识 (料号) Product Identification(Part Number)

QN 0201 X 103 F 3435 F A
① ② ③ ④ ⑤ ⑥ ⑦ ⑧

① 类别 Type	
QN	片式 NTC 热敏电阻器 Chip NTC Thermistor

② 外形尺寸(mm) External Dimensions (L×W×T)	
0201[0603]	0.60×0.30×0.30
0402[1005]	1.00×0.50×0.50
0603[1608]	1.60×0.80×0.80
0805[2012]	2.00×1.25×0.85

③ 分隔符 Delimiter
X

④ 25℃的零功率电阻 Nominal Zero-Power Resistance	
222	2.2kΩ
103	10kΩ
104	100kΩ

⑤ 电阻值公差 Tolerance of Resistance	
F	±1%
G	±2%
H	±3%
J	±5%

⑥ B 值常数 B Constant	
3435	3435K
3950	3950K
4250	4250K

⑦ B 值公差 Tolerance of B Constant	
F	±1%
H	±3%

⑧ B 值计算方式 B constant calculation method	
A	25℃&85℃
B	25℃&50℃

3 电气特性 Electrical Characteristics

型号 Part No	电阻值 Resistance (25℃) (kΩ)	B 常数 B Constant (25/50℃) (K)	B 常数 B Constant (25/85℃) (K)	允许工作电流 Permissible Operating Current (25℃) (mA)	耗散系数 Dissipation Factor (mW/℃)	热时间常数 Thermal Time Constant (s)	额定功率 Rated Electric Power(25℃) (mW)	工作温度 Operating ambient temperature (℃)
QN0201X103F3435FA	10±1%	3380 ref.	3435±1%	0.31	1.0	<3	100	-40~+125

4 检验和测试程序

▪ 测试条件

如无特别规定，检验和测试的标准大气环境条件如下：

- a. 环境温度：20±15℃；
- b. 相对湿度：65±20%；
- c. 气压：86 kPa~106 kPa

如果对测试结果有异议，则在下述条件下测试：

- a. 环境温度：25±2℃；
- b. 相对湿度：65±5%
- c. 气压：86kPa ~ 106kPa

▪ 检查设备

外观检查：20 倍放大镜；

阻值检查：热敏电阻测试仪

4 Test and Measurement Procedures

▪ Test Conditions

Unless otherwise specified, the standard atmospheric conditions for measurement/test as:

- a. Ambient Temperature: 20±15℃
- b. Relative Humidity: 65±20%
- c. Air Pressure: 86kPa to 106kPa

If any doubt on the results, measurements/tests should be made within the following limits:

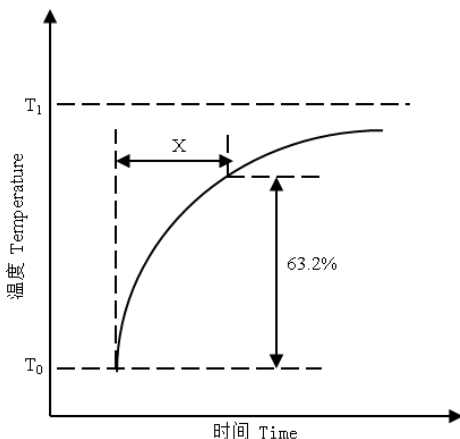
- a. Ambient Temperature: 25±2℃
- b. Relative Humidity: 65±5%
- c. Air Pressure: 86kPa to 106kPa

▪ Inspection Equipment

Visual Examination: 20× magnifier

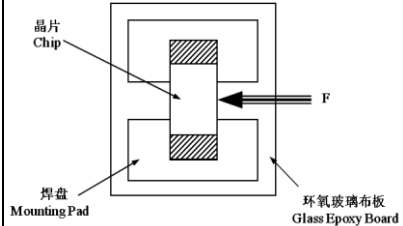
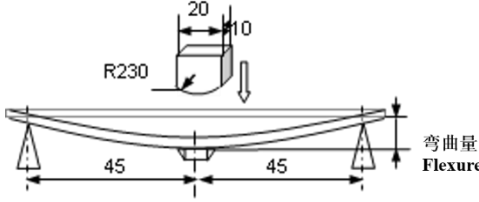
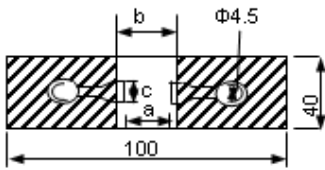
Resistance value test: Thermistor resistance tester

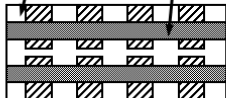
5 电性测试 Electrical Test

序号 No.	项目 Items	测试方法及备注 Test Methods and Remarks
1	25℃ 零功率电阻值 Nominal Zero-Power Resistance at 25℃(R25)	环境温度 Ambient temperature: 25±0.05℃ 测试功率 Measuring electric power: ≤0.1mW
2	B 值常数 Nominal B Constant	分别在环境温度 25±0.05℃, 50±0.05℃或 85±0.05℃下测量电阻值。 Measure the resistance at the ambient temperature of 25±0.05℃, 50±0.05℃ or 85±0.05℃. $B(25-50^{\circ}\text{C}) = \frac{\ln R_{25} - \ln R_{50}}{1/T_{25} - 1/T_{50}} \quad B(25-85^{\circ}\text{C}) = \frac{\ln R_{25} - \ln R_{85}}{1/T_{25} - 1/T_{85}}$ T: 绝对温度 (K) Absolute temperature (K)
3	热时间常数 Thermal Time Constant	在零功率条件下，当热敏电阻的环境温度发生急剧变化时，热敏电阻元件产生最初温度 T₀ 与最终温度 T₁ 两者温度差的 63.2% 的温度变化所需要的时间，通常以秒(S)表示。 The total time for the temperature of the thermistor to change by 63.2% of the difference from ambient temperature T₀ (°C) to T₁ (°C) by the drastic change of the power applied to thermistor from Non-zero Power to Zero-Power state, normally expressed in second(S). 

4	耗散系数 Dissipation Factor	在一定环境温度下，NTC 热敏电阻通过自身发热使其温度升高 1℃时所需要的功率，通常以 mW/℃表示。可由下面公式计算： The required power which makes the NTC thermistor body temperature raise 1℃ through self-heated, normally expressed in milliwatts per degree Celsius (mW/℃). It can be calculated by the following formula: $\delta = \frac{W}{T-T_0}$
5	额定功率 Rated Power	在环境温度 25℃下因自身发热使表面温度升高 100℃所需要的功率。 The necessary electric power makes thermistor's temperature rise 100℃ by self-heating at ambient temperature 25℃.
6	允许工作电流 Permissible operating current	在静止空气中通过自身发热使其升温为 1℃的电流。 The current that keep body temperature of chip NTC on the PC board in still air rising 1℃ by self-heating.

6 信赖性试验 Reliability Test

项目 Items	测试标准 Standard	测试方法及备注 Test Methods and Remarks	要求 Requirements																														
端头附着力 Terminal Strength	IEC 60068-2-21	将晶片焊接在测试基板上（如右图所示的环氧玻璃布板），按箭头所示方向施加作用力； Solder the chip to the testing jig (glass epoxy board shown in the right) using eutectic solder. Then apply a force in the direction of the arrow. <table><tr><td>尺寸 Size</td><td>F</td><td>保持时间 Duration</td></tr><tr><td>0201</td><td>2N</td><td rowspan="3">10±1s</td></tr><tr><td>0402, 0603</td><td>5N</td></tr><tr><td>0805</td><td>10N</td></tr></table>	尺寸 Size	F	保持时间 Duration	0201	2N	10±1s	0402, 0603	5N	0805	10N	端电极无脱落且瓷体无损伤。 No removal or split of the termination or other defects shall occur. 																				
尺寸 Size	F	保持时间 Duration																															
0201	2N	10±1s																															
0402, 0603	5N																																
0805	10N																																
抗弯强度 Resistance to Flexure	IEC 60068-2-21	将晶片焊接在测试基板上（如右图所示的环氧玻璃布板），按下图箭头所示方向施加作用力； Solder the chip to the test jig (glass epoxy board shown in the right) using a eutectic solder. Then apply a force in the direction shown as follow;  <table><tr><td>尺寸 Size</td><td>弯曲变形量 Flexure</td><td>施压速度 Pressurizing Speed</td><td>保持时间 Duration</td></tr><tr><td>0201,</td><td>1mm</td><td rowspan="2"><0.5mm/s</td><td rowspan="2">10±1s</td></tr><tr><td>0402, 0603, 0805</td><td>2mm</td></tr></table>	尺寸 Size	弯曲变形量 Flexure	施压速度 Pressurizing Speed	保持时间 Duration	0201,	1mm	<0.5mm/s	10±1s	0402, 0603, 0805	2mm	① 无外观损伤。 No visible damage. ② $\Delta R_{25}/R_{25} \leq 3\%$ 单位 unit: mm <table><tr><td>类型 Type</td><td>a</td><td>b</td><td>c</td></tr><tr><td>0201</td><td>0.25</td><td>0.3</td><td>0.3</td></tr><tr><td>0402</td><td>0.4</td><td>1.5</td><td>0.5</td></tr><tr><td>0603</td><td>1.0</td><td>3.0</td><td>1.2</td></tr><tr><td>0805</td><td>1.2</td><td>4.0</td><td>1.65</td></tr></table> 	类型 Type	a	b	c	0201	0.25	0.3	0.3	0402	0.4	1.5	0.5	0603	1.0	3.0	1.2	0805	1.2	4.0	1.65
尺寸 Size	弯曲变形量 Flexure	施压速度 Pressurizing Speed	保持时间 Duration																														
0201,	1mm	<0.5mm/s	10±1s																														
0402, 0603, 0805	2mm																																
类型 Type	a	b	c																														
0201	0.25	0.3	0.3																														
0402	0.4	1.5	0.5																														
0603	1.0	3.0	1.2																														
0805	1.2	4.0	1.65																														

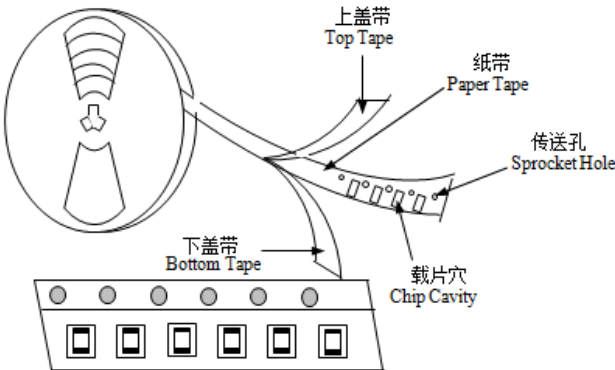
振动 Vibration	IEC 60068-2-80	① 将晶片焊接在测试基板上（如右图所示的环氧玻璃布板）； Solder the chip to the testing jig (glass epoxy board shown in the left) using eutectic solder. ② 晶片以全振幅为 1.5mm 进行振动，频率范围为 10Hz ~55 Hz； The chip shall be subjected to a simple harmonic motion having total amplitude of 1.5mm, the frequency being varied uniformly between the approximate limits of 10 and 55 Hz. ③ 振动频率按 10Hz→55Hz→10Hz 循环，周期为 1 分钟，在空间三个互相垂直的方向上各振动 2 小时（共 6 小时）。 The frequency ranges from 10 to 55 Hz and return to 10 Hz shall be traversed in approximately 1 minute. This motion shall be applied for a period of 2 hours in each 3mutually perpendicular directions (total of 6 hours).	无外观损伤。 No visible damage. 铜箔 Cupad 阻焊膜 Solder mask  环氧玻璃布板Glass Epoxy Board															
坠落 Dropping	IEC 60068-2-32	从 1m 的高度让晶片自由坠落至水泥地面 10 次。 Drop a chip 10 times on a concrete floor from a height of 1 meter.	无外观损伤。 No visible damage.															
可焊性 Solderability	IEC 60068-2-58	① 焊接温度 Solder temperature: 245±5℃. ② 浸渍时间 Duration: 3±0.3s. ③ 焊锡成分 Solder: 96.5Sn/3.0Ag/0.5Cu. ④ 助焊剂 Flux: （重量比）25%松香和 75%酒精 25% Resin and 75% ethanol in weight.	① 无外观损伤； No visible damage. ② 元件端电极的焊锡覆盖率不小于 95%。 Wetting shall exceed 95% coverage.															
耐焊性 Resistance to Soldering Heat	IEC 60068-2-58	① 焊接温度 Solder temperature: 260±5℃. ② 浸渍时间 Duration: 10±1s. ③ 焊锡成分 Solder: 96.5Sn/3.0Ag/0.5Cu. ④ 助焊剂 Flux: （重量比）25%松香和 75%酒精 25% Resin and 75% ethanol in weight. ⑤ 试验后标准条件下放置 1~2 小时后测量。 The chip shall be stabilized at normal condition for 1~2 hours before measuring.	① 无外观损伤； No visible damage. ② ΔR25/R25 ≤3% ③ ΔB/B ≤1%															
温度周期 Temperature cycling	IEC 60068-2-14	① 无负载于下表所示的环境条件下重复 5 次。 5 cycles of following sequence without loading. <table><tr><td>步骤 Step</td><td>温度 Temperature</td><td>时间 Time</td></tr><tr><td>1</td><td>-40±5℃</td><td>30±3min</td></tr><tr><td>2</td><td>25±2℃</td><td>5±3min</td></tr><tr><td>3</td><td>125±2℃</td><td>30±3min</td></tr><tr><td>4</td><td>25±2℃</td><td>5±3min</td></tr></table> ② 试验后标准条件下放置 1~2 小时后测量。 The chip shall be stabilized at normal condition for 1~2 hours before measuring.	步骤 Step	温度 Temperature	时间 Time	1	-40±5℃	30±3min	2	25±2℃	5±3min	3	125±2℃	30±3min	4	25±2℃	5±3min	① 无外观损伤； No visible damage. ② ΔR25/R25 ≤3% ③ ΔB/B ≤1%
步骤 Step	温度 Temperature	时间 Time																
1	-40±5℃	30±3min																
2	25±2℃	5±3min																
3	125±2℃	30±3min																
4	25±2℃	5±3min																
高温存放 Resistance to dry heat	IEC 60068-2-2	① 在 125±5℃空气中，无负载放置 1000±24 小时。 125±5℃ in air, for 1000±24 hours without loading. ② 试验后标准条件下放置 1~2 小时后测量。 The chip shall be stabilized at normal condition for 1~2 hours before measuring.	① 无外观损伤； No visible damage. ② ΔR25/R25 ≤3% ③ ΔB/B ≤1%															

低温存放 Resistance to cold	IEC 60068-2-1	① 在-40±3℃空气中，无负载放置 1000±24 小时。 -40±3℃ in air, for 1000±24 hours without loading. ② 试验后标准条件下放置 1~2 小时后测量。 The chip shall be stabilized at normal condition for 1~2 hours before measuring.	① 无外观损伤； No visible damage. ② ΔR25/R25 ≤3% ③ ΔB/B ≤1%
湿热存放 Resistance to damp heat	IEC 60068-2-78	① 在 60±2℃，相对湿度 90~95%空气中，无负载放置 1000±24 小时。 60±2℃, 90~95%RH in air, for 1000±24 hours without loading. ② 试验后标准条件下放置 1~2 小时后测量。 The chip shall be stabilized at normal condition for 1~2 hours before measuring.	① 无外观损伤； No visible damage. ② ΔR25/R25 ≤3% ③ ΔB/B ≤1%
高温负荷 Resistance to high temperature load	IEC 60539-1 5.25.4	① 在 85±2℃空气中，施加允许工作电流 1000±48 小时。 85±2℃ in air with permissive operating current for 1000±48 hours ② 试验后标准条件下放置 1~2 小时后测量。 The chip shall be stabilized at normal condition for 1~2 hours before measuring.	① 无外观损伤； No visible damage. ② ΔR25/R25 ≤3% ③ ΔB/B ≤1%

7 编带 Taping

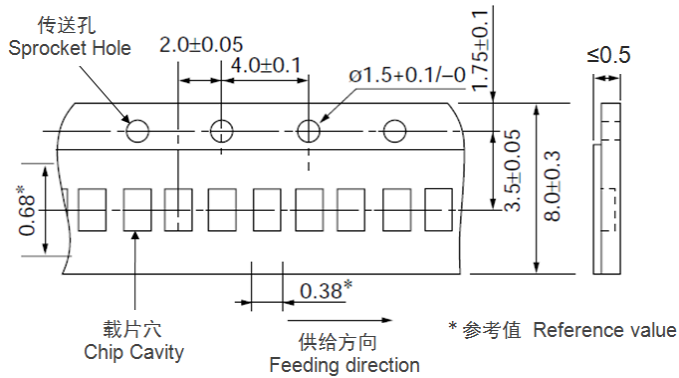
类型 Type	0201	0402	0603	0805
编带厚度 Tape thickness(mm)	0.5±0.15	0.5±0.15	0.8±0.15	0.85±0.2
编带材质 Tape material	纸带 Paper Tape			
每盘数量 Quantity per Reel	15K	10K	4K	4K

(1) 编带图 Taping Drawings

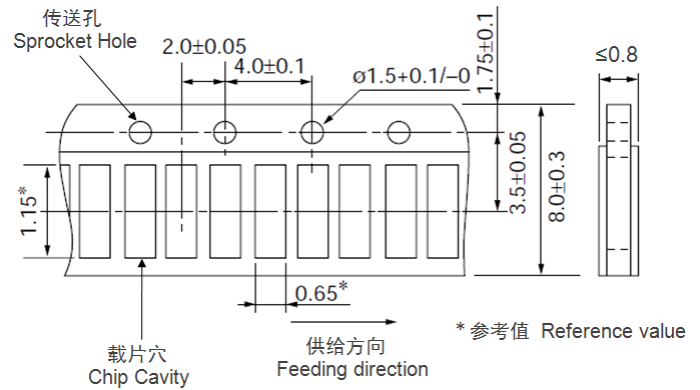


(2) 纸带尺寸 Paper Tape Dimensions (单位 Unit: mm)

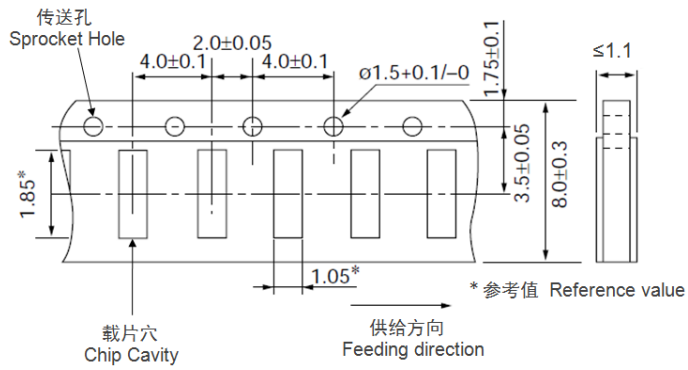
QN0201 系列 QN0201 series



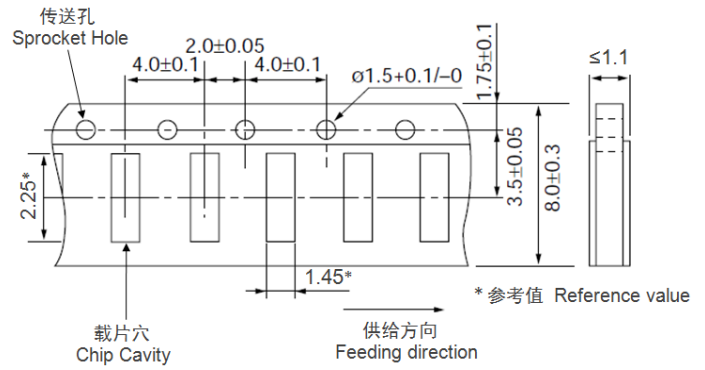
QN0402 系列 QN0402 series



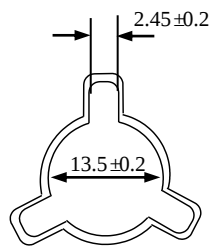
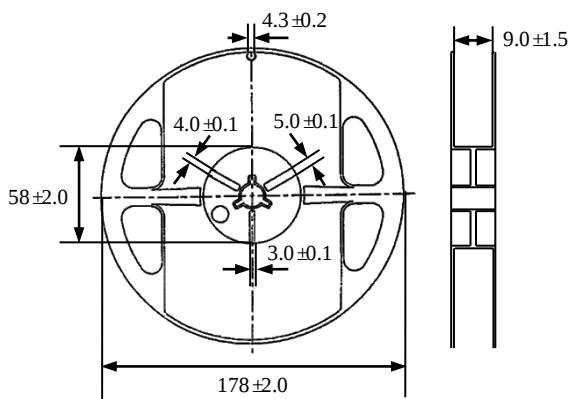
QN0603 系列 QN0603 series



QN0805 系列 QN0805 series



(3) 卷盘尺寸 Reel Dimensions (单位 Unit: mm)



8 储存

• 储存条件

- a. 储存温度: $-10^{\circ}\text{C} \sim 40^{\circ}\text{C}$
- b. 相对湿度: $\leq 75\% \text{RH}$
- c. 避免接触粉尘、腐蚀性气氛和阳光

• 储存期限: 产品交付后 6 个月

9 注意事项

• QN 系列热敏电阻不可在以下条件下工作或储存:

- (1) 腐蚀性气体或还原性气体
(氯气、硫化氢气体、氨气、硫酸气体、一氧化氮等)。
- (2) 挥发性或易燃性气体
- (3) 多尘条件
- (4) 高压或低压条件
- (5) 潮湿场所
- (6) 存在盐水、油、化学液体或有机溶剂的场所
- (7) 强烈振动
- (8) 存在类似有害条件的其他场所

• QN 系列热敏电阻的陶瓷属于易碎材料, 使用时不可施加过大压力或冲击。

• QN 系列热敏电阻不可在超过目录规定的温度范围情况下工作。

8 Storage

• Storage Conditions

- a. Storage Temperature: $-10^{\circ}\text{C} \sim 40^{\circ}\text{C}$
- b. Relative Humidity: $\leq 75\% \text{RH}$
- c. Keep away from corrosive atmosphere and sunlight.

• Period of Storage: 6 Months after delivery

9 Notes & Warnings

• The QN series thermistors shall not be operated and stored under the following environmental condition:

- (1) Corrosive or deoxidized atmospheres
(such as chlorine, sulfurated hydrogen, ammonia, sulfuric acid, nitric oxide and so on)
- (2) Volatile or inflammable atmospheres
- (3) Dusty condition
- (4) Excessively high or low pressure condition
- (5) Humid site
- (6) Places with brine, oil, chemical liquid or organic solvent
- (7) Intense vibration
- (8) Places with analogously deleterious conditions

• The ceramic body of the QN series thermistors is fragile, no excessive pressure or impact shall be exerted on it.

• The QN series thermistors shall not be operated beyond the specified "Operating Temperature Range" in the catalog.

10 建议焊接条件

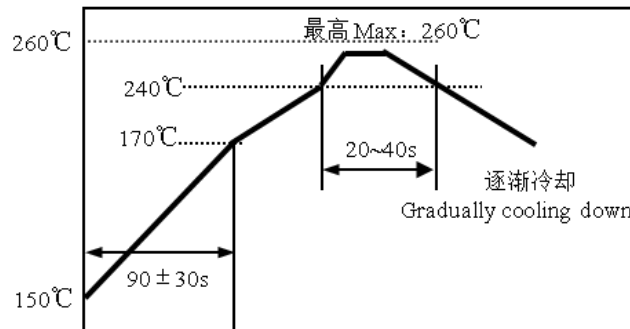
• 回流焊

- 温升 1~2°C/sec.
- 预热: 150~170°C/90±30 sec.
- 大于 240°C 时间: 20~40sec
- 峰值温度: 最高 260°C/10 sec.
- 焊锡: 96.5Sn/3.0Ag/0.5Cu
- 回流焊: 最多 2 次

10 Recommended Soldering Technologies

• Re-flowing Profile

- 1~2°C/sec. Ramp
- Pre-heating: 150~170°C/90±30 sec.
- Time above 240°C: 20~40 sec.
- Peak temperature: 260°C Max./10 sec.
- Solder paste: 96.5Sn/3.0Ag/0.5Cu
- Max.2 times for re-flowing



• 手工焊

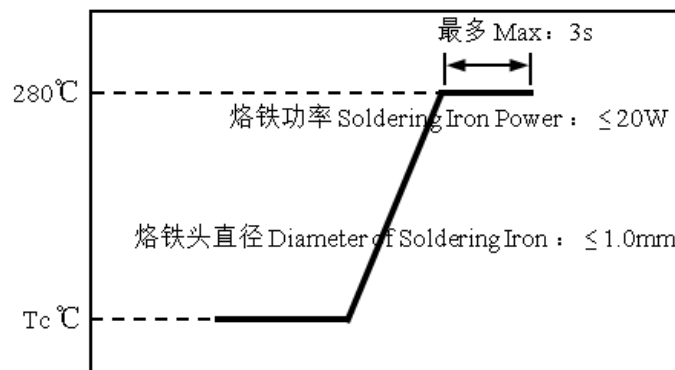
- 烙铁功率: 最大 20W
- 预热: 150°C/60sec.
- 烙铁头温度: 最高 280°C
- 焊接时间: 最多 3sec.
- 焊锡: 96.5Sn/3.0Ag/0.5Cu
- 手工焊: 最多 1 次

• Iron Soldering Profile

- Iron soldering power: Max.20W
- Pre-heating: 150°C/60sec.
- Soldering Tip temperature: 280°C Max.
- Soldering time: 3 sec Max.
- Solder paste: 96.5Sn/3.0Ag/0.5Cu
- Max.1 times for iron soldering

[注: 不要使烙铁头接触到端头]

[Note: Take care not to apply the tip of the soldering iron to the terminal electrodes.]



11 R-T 表 R-T table

QN0201X103F3435FA

温度 Temp. (°C)	R 最小值 R_Min (Kohm)	R 中心值 R_Cent (Kohm)	R 最大值 R_Max (Kohm)	阻值公差 Res TOL.	温度公差 Temp. TOL.(°C)
-40	189.674	197.390	205.400	4.06%	0.69
-39	179.349	186.540	194.000	4.00%	0.69
-38	169.647	176.350	183.299	3.94%	0.68
-37	160.550	166.800	173.276	3.88%	0.68
-36	151.990	157.820	163.857	3.83%	0.67
-35	143.951	149.390	155.019	3.77%	0.67
-34	136.431	141.510	146.763	3.71%	0.66
-33	129.347	134.090	138.993	3.66%	0.66
-32	122.680	127.110	131.687	3.60%	0.65
-31	116.391	120.530	124.804	3.55%	0.65
-30	110.472	114.340	118.332	3.49%	0.64
-29	104.913	108.530	112.260	3.44%	0.64
-28	99.658	103.040	106.526	3.38%	0.63
-27	94.706	97.870	101.129	3.33%	0.63
-26	90.029	92.989	96.037	3.28%	0.62
-25	85.611	88.381	91.231	3.23%	0.62
-24	81.443	84.036	86.702	3.17%	0.61
-23	77.504	79.931	82.426	3.12%	0.60
-22	73.779	76.052	78.387	3.07%	0.60
-21	70.256	72.384	74.569	3.02%	0.59
-20	66.922	68.915	70.961	2.97%	0.59
-19	63.767	65.634	67.549	2.92%	0.58
-18	60.779	62.529	64.323	2.87%	0.58
-17	57.949	59.589	61.269	2.82%	0.57
-16	55.268	56.804	58.377	2.77%	0.56
-15	52.726	54.166	55.640	2.72%	0.56
-14	50.315	51.665	53.046	2.67%	0.55
-13	48.029	49.294	50.588	2.62%	0.55
-12	45.860	47.046	48.258	2.58%	0.54
-11	43.801	44.913	46.049	2.53%	0.53
-10	41.846	42.889	43.953	2.48%	0.53
-9	39.989	40.967	41.964	2.43%	0.52
-8	38.225	39.142	40.077	2.39%	0.51
-7	36.549	37.408	38.284	2.34%	0.51
-6	34.955	35.761	36.582	2.30%	0.50
-5	33.440	34.196	34.965	2.25%	0.49
-4	31.998	32.707	33.428	2.20%	0.49
-3	30.627	31.291	31.966	2.16%	0.48
-2	29.322	29.945	30.578	2.11%	0.47
-1	28.080	28.664	29.257	2.07%	0.47
0	26.898	27.445	28.001	2.02%	0.46
1	25.770	26.283	26.804	1.98%	0.45

温度 Temp. (°C)	R 最小值 R_Min (Kohm)	R 中心值 R_Cent (Kohm)	R 最大值 R_Max (Kohm)	阻值公差 Res TOL.	温度公差 Temp. TOL.(°C)
2	24.696	25.177	25.665	1.94%	0.45
3	23.673	24.124	24.581	1.89%	0.44
4	22.699	23.121	23.549	1.85%	0.43
5	21.769	22.165	22.566	1.81%	0.42
6	20.882	21.253	21.628	1.76%	0.42
7	20.037	20.384	20.735	1.72%	0.41
8	19.230	19.555	19.883	1.68%	0.40
9	18.460	18.764	19.071	1.64%	0.39
10	17.725	18.010	18.297	1.60%	0.39
11	17.024	17.290	17.559	1.55%	0.38
12	16.353	16.602	16.853	1.51%	0.37
13	15.713	15.946	16.181	1.47%	0.36
14	15.101	15.319	15.538	1.43%	0.36
15	14.517	14.720	14.925	1.39%	0.35
16	13.958	14.148	14.339	1.35%	0.34
17	13.424	13.601	13.779	1.31%	0.33
18	12.913	13.078	13.244	1.27%	0.32
19	12.424	12.578	12.733	1.23%	0.32
20	11.955	12.099	12.243	1.19%	0.31
21	11.508	11.642	11.776	1.15%	0.30
22	11.079	11.204	11.329	1.11%	0.29
23	10.669	10.785	10.901	1.08%	0.28
24	10.276	10.384	10.492	1.04%	0.27
25	9.900	10.000	10.100	1.00%	0.27
26	9.532	9.632	9.732	1.04%	0.28
27	9.180	9.280	9.380	1.08%	0.29
28	8.843	8.943	9.042	1.11%	0.30
29	8.520	8.619	8.718	1.15%	0.31
30	8.211	8.309	8.408	1.19%	0.33
31	7.914	8.012	8.110	1.22%	0.34
32	7.630	7.727	7.824	1.26%	0.35
33	7.357	7.453	7.550	1.30%	0.36
34	7.096	7.191	7.287	1.33%	0.37
35	6.845	6.939	7.034	1.37%	0.39
36	6.604	6.698	6.792	1.41%	0.40
37	6.373	6.466	6.559	1.44%	0.41
38	6.152	6.243	6.335	1.48%	0.43
39	5.939	6.029	6.120	1.51%	0.44
40	5.735	5.824	5.914	1.55%	0.45
41	5.538	5.627	5.716	1.58%	0.46
42	5.350	5.437	5.525	1.62%	0.48
43	5.169	5.255	5.342	1.65%	0.49
44	4.995	5.080	5.165	1.69%	0.50
45	4.828	4.911	4.996	1.72%	0.52
46	4.667	4.749	4.832	1.75%	0.53

温度 Temp. (°C)	R 最小值 R_Min (Kohm)	R 中心值 R_Cent (Kohm)	R 最大值 R_Max (Kohm)	阻值公差 Res TOL.	温度公差 Temp. TOL.(°C)
47	4.512	4.593	4.675	1.79%	0.54
48	4.363	4.443	4.524	1.82%	0.56
49	4.220	4.299	4.379	1.86%	0.57
50	4.083	4.160	4.239	1.89%	0.58
51	3.950	4.027	4.104	1.92%	0.60
52	3.823	3.898	3.974	1.96%	0.61
53	3.700	3.774	3.849	1.99%	0.63
54	3.582	3.654	3.728	2.02%	0.64
55	3.468	3.539	3.612	2.05%	0.65
56	3.358	3.429	3.500	2.09%	0.67
57	3.252	3.322	3.392	2.12%	0.68
58	3.151	3.219	3.288	2.15%	0.70
59	3.052	3.119	3.188	2.18%	0.71
60	2.958	3.024	3.091	2.22%	0.72
61	2.867	2.931	2.997	2.25%	0.74
62	2.779	2.842	2.907	2.28%	0.75
63	2.694	2.756	2.820	2.31%	0.77
64	2.612	2.673	2.736	2.34%	0.78
65	2.533	2.593	2.655	2.37%	0.80
66	2.457	2.516	2.576	2.40%	0.81
67	2.383	2.441	2.501	2.43%	0.83
68	2.312	2.369	2.428	2.46%	0.84
69	2.244	2.300	2.357	2.50%	0.86
70	2.177	2.233	2.289	2.53%	0.87
71	2.113	2.168	2.223	2.56%	0.89
72	2.052	2.105	2.159	2.59%	0.90
73	1.992	2.044	2.098	2.62%	0.92
74	1.934	1.986	2.038	2.65%	0.93
75	1.879	1.929	1.981	2.68%	0.95
76	1.825	1.874	1.925	2.71%	0.96
77	1.773	1.821	1.871	2.73%	0.98
78	1.722	1.770	1.819	2.76%	1.00
79	1.673	1.720	1.768	2.79%	1.01
80	1.626	1.673	1.720	2.82%	1.03
81	1.581	1.626	1.672	2.85%	1.04
82	1.537	1.581	1.627	2.88%	1.06
83	1.494	1.538	1.582	2.91%	1.08
84	1.453	1.496	1.540	2.94%	1.09
85	1.413	1.455	1.498	2.97%	1.11
86	1.374	1.416	1.458	2.99%	1.13
87	1.337	1.377	1.419	3.02%	1.14
88	1.300	1.340	1.381	3.05%	1.16
89	1.265	1.304	1.345	3.08%	1.17
90	1.231	1.270	1.309	3.11%	1.19
91	1.198	1.236	1.275	3.13%	1.21

温度 Temp. (°C)	R 最小值 R_Min (Kohm)	R 中心值 R_Cent (Kohm)	R 最大值 R_Max (Kohm)	阻值公差 Res TOL.	温度公差 Temp. TOL.(°C)
92	1.167	1.204	1.242	3.16%	1.23
93	1.136	1.172	1.209	3.19%	1.24
94	1.106	1.141	1.178	3.22%	1.26
95	1.076	1.112	1.148	3.24%	1.28
96	1.048	1.083	1.118	3.27%	1.29
97	1.021	1.055	1.090	3.30%	1.31
98	0.995	1.028	1.062	3.32%	1.33
99	0.969	1.002	1.035	3.35%	1.35
100	0.944	0.976	1.009	3.38%	1.36
101	0.920	0.951	0.984	3.40%	1.38
102	0.897	0.927	0.959	3.43%	1.40
103	0.874	0.904	0.935	3.46%	1.42
104	0.852	0.882	0.912	3.48%	1.43
105	0.830	0.860	0.890	3.51%	1.45
106	0.810	0.838	0.868	3.53%	1.47
107	0.790	0.818	0.847	3.56%	1.49
108	0.770	0.798	0.826	3.59%	1.50
109	0.751	0.778	0.806	3.61%	1.52
110	0.733	0.759	0.787	3.64%	1.54
111	0.715	0.741	0.768	3.66%	1.56
112	0.697	0.723	0.750	3.69%	1.58
113	0.680	0.706	0.732	3.71%	1.60
114	0.664	0.689	0.715	3.74%	1.61
115	0.648	0.673	0.698	3.76%	1.63
116	0.633	0.657	0.682	3.79%	1.65
117	0.618	0.641	0.666	3.81%	1.67
118	0.603	0.626	0.650	3.84%	1.69
119	0.589	0.612	0.635	3.86%	1.71
120	0.575	0.598	0.621	3.89%	1.73
121	0.562	0.584	0.607	3.91%	1.75
122	0.549	0.570	0.593	3.93%	1.77
123	0.536	0.557	0.579	3.96%	1.79
124	0.524	0.545	0.566	3.98%	1.80
125	0.512	0.532	0.554	4.01%	1.82